



## Material Content Data Sheet



Sales Product Name	IPP90N04S4-02			Issued		20. July 2016		
MA#	MA001029744							
Package	PG-TO220-3-1			Weight*		2035.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	0.22	0.22	2174	2174
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		401	
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	copper	7440-50-8	815.335	40.06	40.11	400491	401013
wire	non noble metal	aluminium	7429-90-5	6.219	0.31	0.31	3055	3055
encapsulation	organic material	carbon black	1333-86-4	8.901	0.44		4372	
	plastics	epoxy resin	-	97.915	4.81		48096	
	inorganic material	silicondioxide	60676-86-0	486.609	23.90	29.15	239022	291490
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10542	10542
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	120
solder	noble metal	silver	7440-22-4	0.086	0.00		42	
	non noble metal	tin	7440-31-5	0.069	0.00		34	
	non noble metal	lead	7439-92-1	3.272	0.16	0.16	1607	1683
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		290	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	copper	7440-50-8	589.466	28.95	28.99	289546	289923
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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